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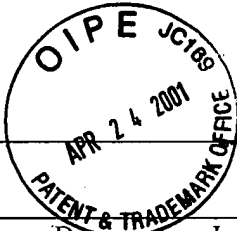
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STATEMENT BY APPLICANT

Harald S. Gross
Applicants

(Use several sheets if necessary)

December 13, 2000
Filing Date

Unknown
Group



U. S. PATENT DOCUMENTS

Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
<u>QTA</u>	4,609,968	09/02/86	Wilner	361	320	—
<u>QTA</u>	4,802,952	02/07/89	Kobori et al.	156	634	—
<u>QTA</u>	5,141,148	08/25/92	Ichiyawa	228	263	—
<u>QTA</u>	5,411,919	05/02/95	Inada	437	209	—
<u>QTA</u>	5,528,070	06/18/96	Cahill	257	419	—
<u>QTA</u>	5,783,309	07/21/98	Faure et al.	428	432	—
<u>QTA</u>	5,938,911	08/17/99	Quenzer et al.	205	114	—

Examiner _____ Date Considered _____

Th T. Hara 12/10/01

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FOREIGN PATENT DOCUMENTS

09/239,078

Examiner Initial	Document Number	Publication Date	Name	Class	Subclass	Translation If Appropriate
<i>[Signature]</i>	DE 4136075	05/06/93	F. Arndt et al.	H01L	021/58	Abstract only
<i>[Signature]</i>	JP 2141442	05/30/90	Mitsubishi Denki KK	C03C	027/00	Abstract only

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

[Signature] S. Shoji et al., "Anodic Bonding Below 180°C for Packaging and Assembling MEMS Using Aluminosilicate-β-quartz Glass-Ceramic", IEEE Document No. 0-7803-3744-1/97.

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